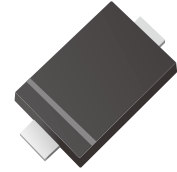


Surface Mount General Purpose Silicon Rectifier
Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives


Mechanical Data

- Case: SOD-123FL
- Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end


Ordering Information

Part Number	Marking	Shipping	Reel
LTGA7-TR3	A7	3000PCS Tape&Reel	7 inches
LTGA7-TR12	A7	12000PCS Tape&Reel	13 inches

Maximum Ratings and Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbol	LTGA7	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30	A
Maximum Instantaneous Forward Voltage at 1 A	V_F	1.1	V
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125^\circ\text{C}$	I_R	5 50	μA
Typical Junction Capacitance (NOTE1)	C_j	8(TYP.)	pF
Typical Thermal Resistance (NOTE2)	$R_{\theta JA}$ $R_{\theta JC}$	115 25	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	$^\circ\text{C}$

Note:(1) Measured at 1 MHz and applied reverse voltage of 4V D.C.

(2) P.C.B. mounted with 2.0" x 2.0" (5cm x 5cm) copper pad areas.



Characteristics Curves

Fig.1 Forward Current Derating Curve

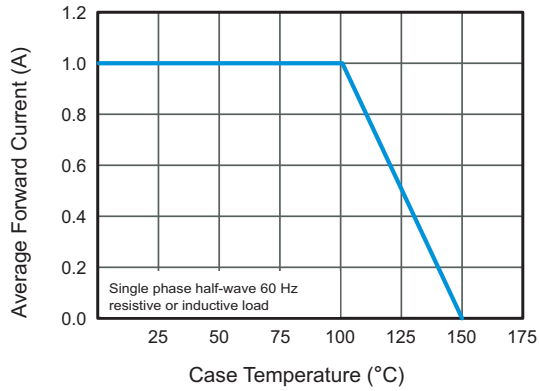


Fig.2 Typical Instaneous Reverse Characteristics

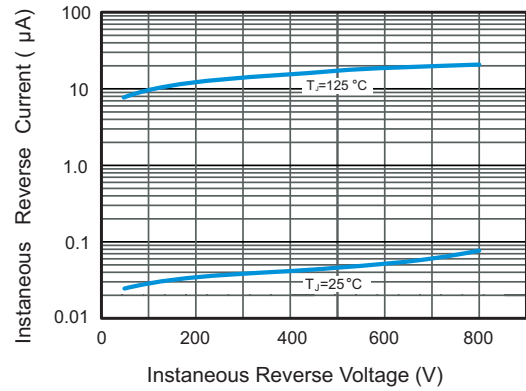


Fig.3 Typical Forward Characteristic

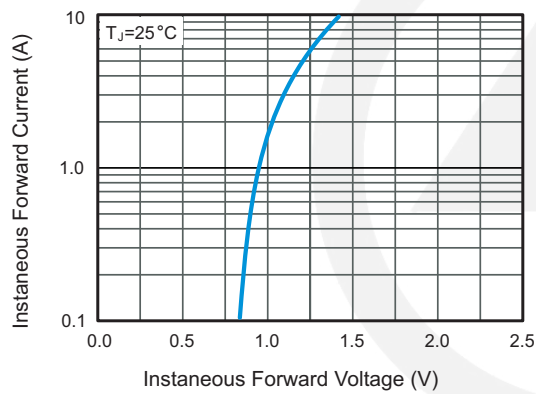


Fig.4 Typical Junction Capacitance

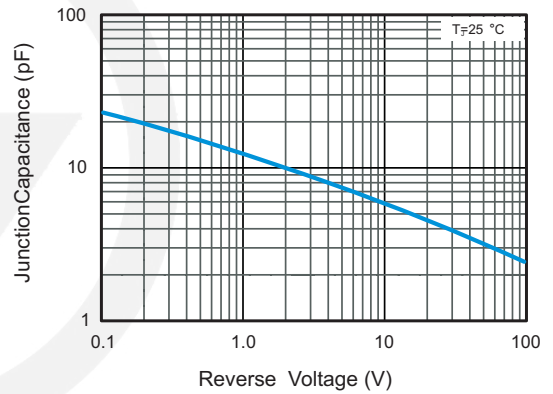
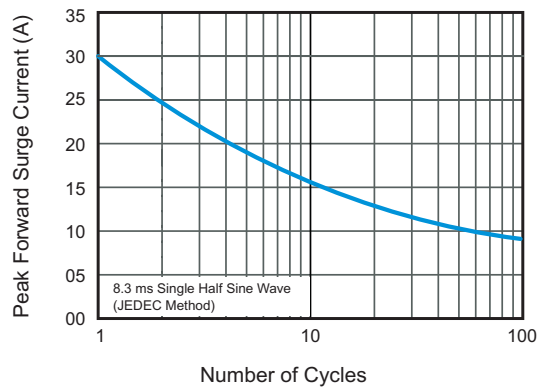
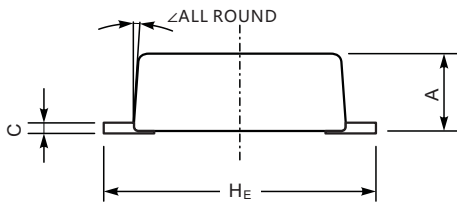


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

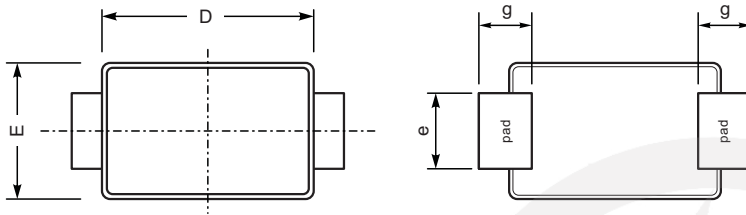


SOD-123FL Package Outline

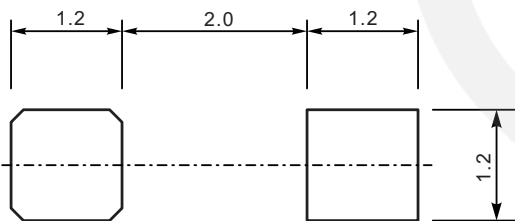
Unit: mm



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.9	1.35
C	0.12	0.20
D	2.6	2.9
E	1.75	1.95
e	0.8	1.1
g	0.7	0.9
H _E	3.5	3.8
∠	7°	



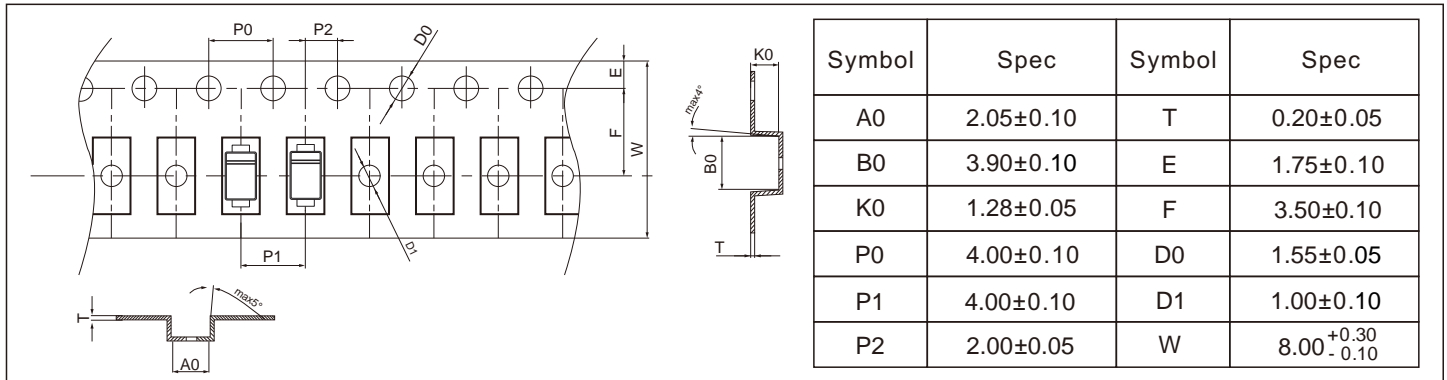
SOD-123FL Suggested Pad Layout



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: ± 0.05mm
 3. The pad layout is for reference purpose only.

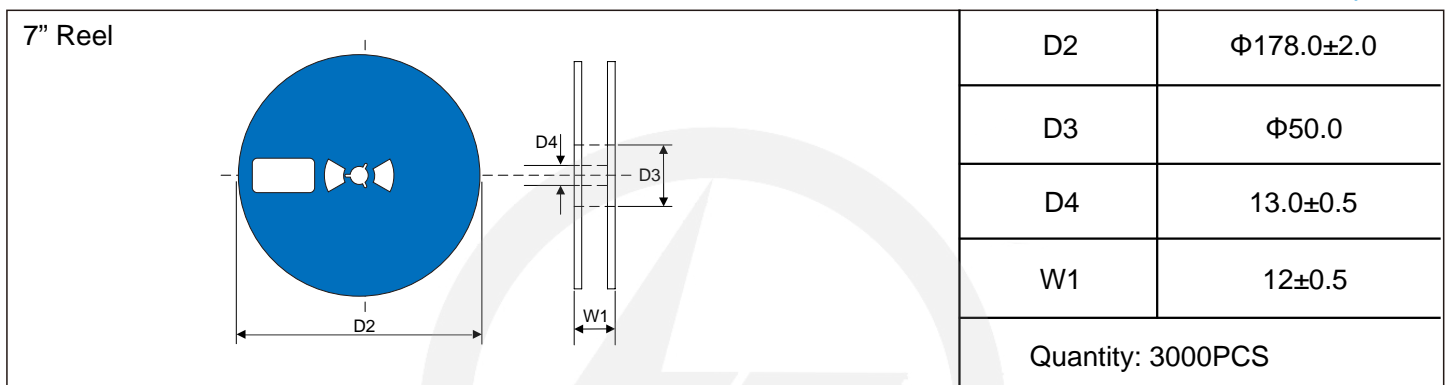
Carrier Tape Dimensions

Unit : mm



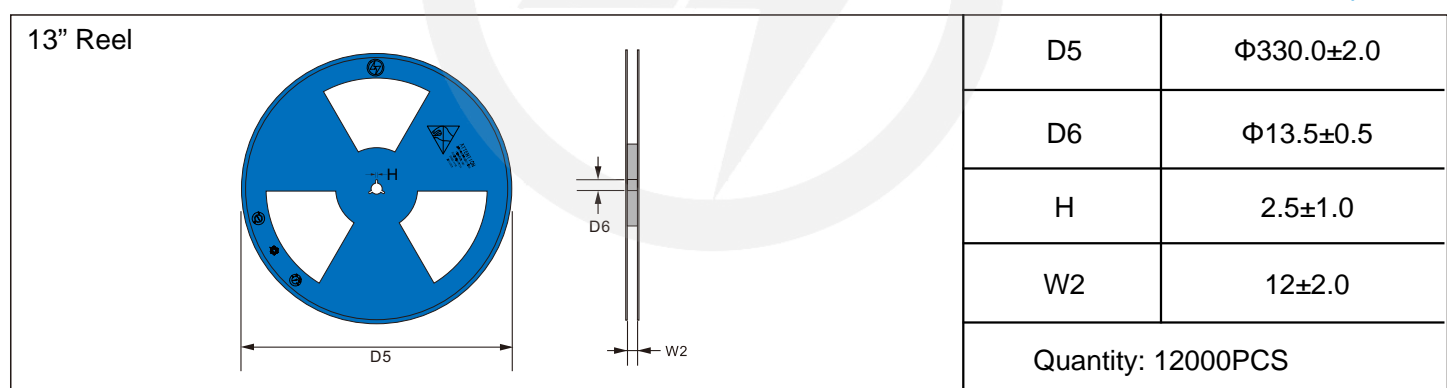
Reel Dimensions

Unit : mm

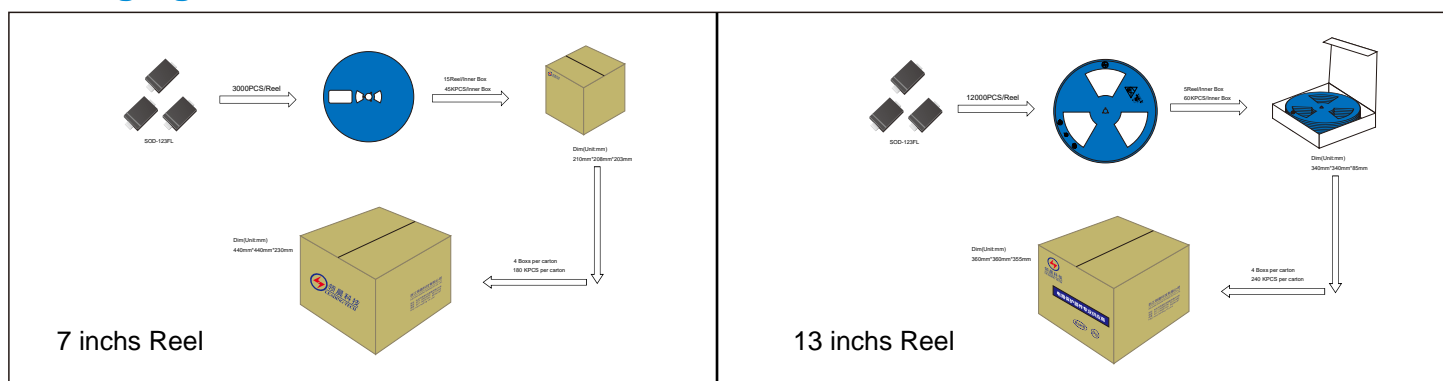


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat	
-Temperature Min ($T_{S\ min}$)	150°C
-Temperature Max ($T_{S\ max}$)	200°C
-Time (min to max) (t_s)	60-180 seconds
$T_{S\ max}$ to T_L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2024.8.25	2024.8.25	3.0	New File	/	Ding	
02	2025.06.12	2025.06.12	3.1	Update packaging information	/	Ding	